

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTF3035EJ	**Issued**	27. April 2022
MA#	MA005738654		
Package	PG-TDSO-8-31	**Weight***	67.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.433	3.59	3.59	35896	35896
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		140	
	non noble metal	zinc	7440-66-6	0.038	0.06		560	
	non noble metal	iron	7439-89-6	0.760	1.12		11209	
	non noble metal	copper	7440-50-8	30.851	45.51	46.70	455121	467030
wire	non noble metal	copper	7440-50-8	0.451	0.66	0.66	6648	6648
encapsulation	organic material	carbon black	1333-86-4	0.093	0.14		1378	
	plastics	epoxy resin	-	3.642	5.37		53726	
	inorganic material	silicondioxide	60676-86-0	27.391	40.41	45.92	404090	459194
leadfinish	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7335	7335
plating	noble metal	silver	7440-22-4	0.825	1.22	1.22	12167	12167
glue	plastics	epoxy resin	-	0.139	0.21		2053	
	noble metal	silver	7440-22-4	0.656	0.97	1.18	9677	11730
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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